

IV. AMENDMENTS TO THE CLAIMS.

This listing of claims replaces all prior versions, and listings, of claims of the application.

1. (Currently amended) A method of manufacturing a semiconductor device (10) which is suitable for surface mounting and which includes a semiconductor body (1) comprising an active element provided with connection regions (2) situated at the surface of the semiconductor body (1), an electrically insulating medium layer (3) being provided, on one of its sides, with a conductor pattern (4) which is suitable for surface mounting, and, on the other side, with the semiconductor body (1), the connection regions (2) of the active element being connected to the conductor pattern (4) by means of electrically conductive vias (5) in the insulating medium layer (3), ~~characterized in that the electrically insulating medium layer (3) provided with the conductor pattern (4) is formed by a flexible foil (6) comprising a conductive layer (4) and an electrically insulating layer (3), which flexible foil is detachably secured to a substrate (7) on the side of the conductor pattern (4) formed in the conductive layer (4)~~ the method including the steps of:

forming the conductor pattern (4) and the insulating layer (3) on a flexible foil (6), wherein the flexible foil (6) originally comprises a conductive layer and an electrically insulating layer; and

detachably securing the flexible foil (6) to a substrate (7) on the side of the conductor pattern (4).

2. (Currently amended) A method as claimed in claim 1, characterized in that the electrically conductive vias (5) are formed by providing the insulating layer (3) with apertures (5), as a result of which parts of the conductor pattern (4) in the conductive layer (4) are exposed, and introducing solder (8) into said apertures, as a result of which

the connection regions (2) of the semiconductor body (1) are electrically connected to the conductor pattern (4).

3. (Currently Amended) A method as claimed in claim 1, characterized in that prior to the formation of the electrically conductive vias (5) and prior to the provision of the semiconductor body (1) on the flexible foil (6) that is detachably secured to the substrate (7), the flexible foil (6) is detachably secured, on the side of the insulating layer (3), to another substrate (9), after which the conductor pattern (4) is formed in the conductive layer (4), whereafter the flexible foil (6) is detachably secured, on the side of the conductive layer pattern (4), to the substrate (7), after which the other substrate (9) is removed.

4. (Cancelled).

5. (Currently amended) A method as claimed in claim 1, characterized in that prior to the provision of the semiconductor body (1) on the flexible foil (6), a part thereof that is situated between the ~~apertures~~ conductive vias (5) in the insulating layer (3) is provided with an electrically insulating fixing agent (12) on which the semiconductor body (1) is placed and the height of which determines the distance between the semiconductor body (1) and the flexible foil (6).

6-7. (Cancelled).

8. (Currently amended) A method as claimed in claim 1, characterized in that a solid photoresist ~~layer (3)~~ material is used for the electrically insulating layer (3).

9. (Currently amended) A method as claimed in claim 1, characterized in that for the material of the electrically insulating layer (3) use is made of a polyimide, and for the material of the conductive ~~layer~~ pattern (4) use is made of copper.

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10. (Previously Amended) A semiconductor device (10) which can suitably be used for surface mounting and which is obtained using a method as claimed in claim 1.

11. (New) A method of manufacturing a semiconductor device which is suitable for surface mounting and which includes a semiconductor body comprising an active element provided with connection regions situated at the surface of the semiconductor body, an electrically insulating layer being provided, on one of its sides, with a conductor pattern which is suitable for surface mounting, and, on the other side, with the semiconductor body, the connection regions of the active element being connected to the conductor pattern by means of electrically conductive vias in the insulating layer, the method including the steps of:

forming the conductor pattern and the insulating layer on a flexible foil, wherein the flexible foil originally comprises a conductive layer and an electrically insulating layer;

detachably securing the flexible foil to a substrate on the side of the insulating layer; and

detachably securing the flexible foil to a substrate on the side of the conductor pattern.

12. (New) A method of manufacturing a semiconductor device which is suitable for surface mounting and which includes a semiconductor body comprising an active element provided with connection regions situated at the surface of the semiconductor body, an electrically insulating layer being provided, on one of its sides, with a conductor pattern which is suitable for surface mounting, and, on the other side, with the semiconductor body, the connection regions of the active element being connected to the conductor pattern by means of electrically conductive vias in the insulating layer, the method including the steps of:

forming the conductor pattern and the insulating layer on a flexible foil, wherein the flexible foil originally comprises a conductive layer and an electrically insulating layer;

detachably securing the flexible foil to a substrate on the side of the conductor pattern;

providing an electrically insulating fixing agent between the conductive vias in the insulating layer; and

placing the semiconductor body on the electrically insulating fixing agent, wherein a height of the electrically insulating fixing agent determines a distance between the semiconductor body and the flexible foil.